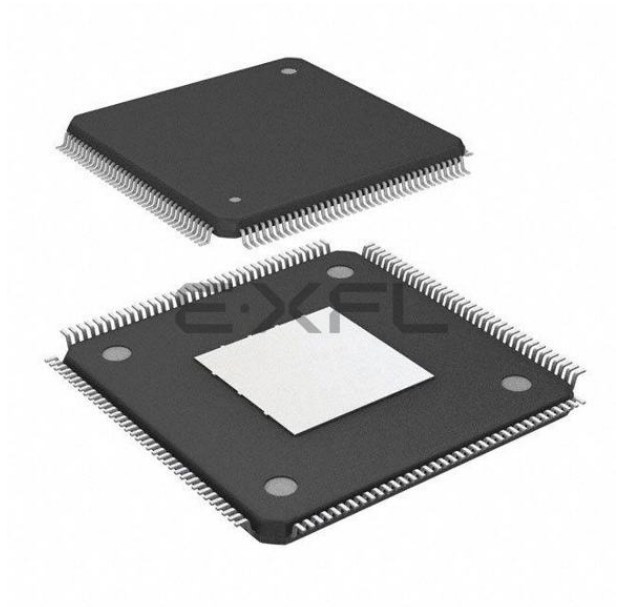


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

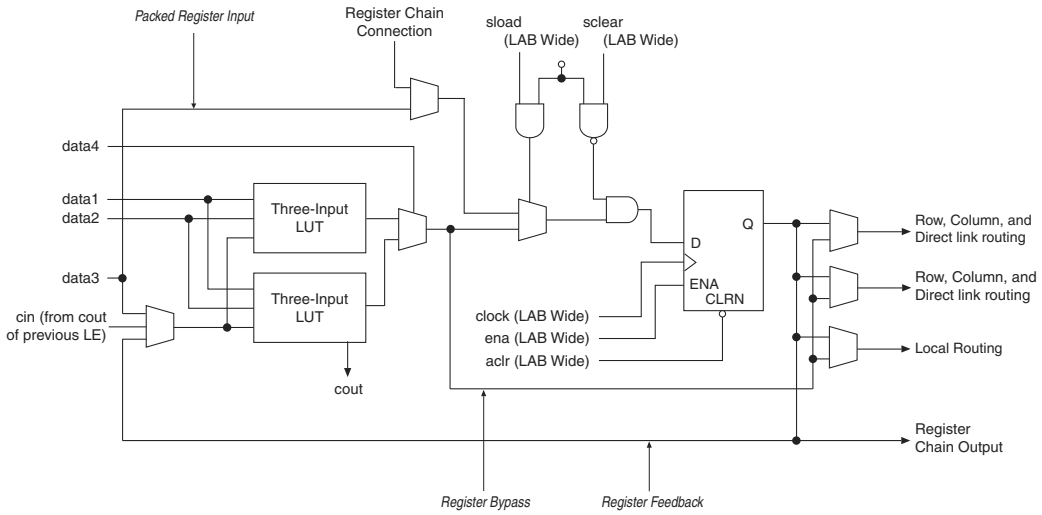
Details	
Product Status	Active
Number of LABs/CLBs	963
Number of Logic Elements/Cells	15408
Total RAM Bits	516096
Number of I/O	81
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-EQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce15e22i7

Arithmetic Mode

Arithmetic mode is ideal for implementing adders, counters, accumulators, and comparators. An LE in arithmetic mode implements a 2-bit full adder and basic carry chain (Figure 2–3). LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output. Register feedback and register packing are supported when LEs are used in arithmetic mode.

Figure 2–3 shows LEs in arithmetic mode.

Figure 2–3. Cyclone IV Device LEs in Arithmetic Mode



The Quartus II Compiler automatically creates carry chain logic during design processing. You can also manually create the carry chain logic during design entry. Parameterized functions, such as LPM functions, automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 16 LEs by automatically linking LABs in the same column. For enhanced fitting, a long carry chain runs vertically, which allows fast horizontal connections to M9K memory blocks or embedded multipliers through direct link interconnects. For example, if a design has a long carry chain in an LAB column next to a column of M9K memory blocks, any LE output can feed an adjacent M9K memory block through the direct link interconnect. If the carry chains run horizontally, any LAB which is not next to the column of M9K memory blocks uses other row or column interconnects to drive a M9K memory block. A carry chain continues as far as a full column.

Clocking Modes

Cyclone IV devices M9K memory blocks support the following clocking modes:

- Independent
- Input or output
- Read or write
- Single-clock

When using read or write clock mode, if you perform a simultaneous read or write to the same address location, the output read data is unknown. If you require the output data to be a known value, use either single-clock mode or I/O clock mode and choose the appropriate read-during-write behavior in the MegaWizard Plug-In Manager.

Violating the setup or hold time on the memory block input registers might corrupt the memory contents. This applies to both read and write operations.

Asynchronous clears are available on read address registers, output registers, and output latches only.

Table 3–5 lists the clocking mode versus memory mode support matrix.

Table 3–5. Cyclone IV Devices Memory Clock Modes

Clocking Mode	True Dual-Port Mode	Simple Dual-Port Mode	Single-Port Mode	ROM Mode	FIFO Mode
Independent	✓	—	—	✓	—
Input or output	✓	✓	✓	✓	—
Read or write	—	✓	—	—	✓
Single-clock	✓	✓	✓	✓	✓

Independent Clock Mode

Cyclone IV devices M9K memory blocks can implement independent clock mode for true dual-port memories. In this mode, a separate clock is available for each port (port A and port B). `clock A` controls all registers on the port A side, while `clock B` controls all registers on the port B side. Each port also supports independent clock enables for port A and B registers.

Input or Output Clock Mode

Cyclone IV devices M9K memory blocks can implement input or output clock mode for FIFO, single-port, true, and simple dual-port memories. In this mode, an input clock controls all input registers to the memory block including data, address, `byteena`, `wren`, and `rden` registers. An output clock controls the data-output registers. Each memory block port also supports independent clock enables for input and output registers.

Power-Up Conditions and Memory Initialization

The M9K memory block outputs of Cyclone IV devices power up to zero (cleared) regardless of whether the output registers are used or bypassed. All M9K memory blocks support initialization using a **.mif**. You can create **.mif**s in the Quartus II software and specify their use using the RAM MegaWizard Plug-In Manager when instantiating memory in your design. Even if memory is pre-initialized (for example, using a **.mif**), it still powers up with its outputs cleared. Only the subsequent read after power up outputs the pre-initialized values.

For more information about **.mif**s, refer to the *RAM Megafunction User Guide* and the *Quartus II Handbook*.

Power Management

The M9K memory block clock enables of Cyclone IV devices allow you to control clocking of each M9K memory block to reduce AC power consumption. Use the `rden` signal to ensure that read operations only occur when necessary. If your design does not require read-during-write, reduce power consumption by deasserting the `rden` signal during write operations or any period when there are no memory operations. The Quartus II software automatically powers down any unused M9K memory blocks to save static power.

Document Revision History

Table 3–6 shows the revision history for this chapter.

Table 3–6. Document Revision History

Date	Version	Changes
November 2011	1.1	Updated the “Byte Enable Support” section.
November 2009	1.0	Initial release.

Table 7–1 lists the number of DQS or DQ groups supported on each side of the Cyclone IV GX device.

Table 7–1. Cyclone IV GX Device DQS and DQ Bus Mode Support for Each Side of the Device

Device	Package	Side	Number ×8 Groups	Number ×9 Groups	Number ×16 Groups	Number ×18 Groups	Number ×32 Groups	Number ×36 Groups
EP4CGX15	169-pin FBGA	Right	1	0	0	0	—	—
		Top (1)	1	0	0	0	—	—
		Bottom (2)	1	0	0	0	—	—
EP4CGX22 EP4CGX30	169-pin FBGA	Right	1	0	0	0	—	—
		Top (1)	1	0	0	0	—	—
		Bottom (2)	1	0	0	0	—	—
	324-pin FBGA	Right	2	2	1	1	—	—
		Top	2	2	1	1	—	—
		Bottom	2	2	1	1	—	—
	484-pin FBGA (3)	Right	4	2	2	2	1	1
		Top	4	2	2	2	1	1
		Bottom	4	2	2	2	1	1
EP4CGX50 EP4CGX75	484-pin FBGA	Right	4	2	2	2	1	1
		Top	4	2	2	2	1	1
		Bottom	4	2	2	2	1	1
	672-pin FBGA	Right	4	2	2	2	1	1
		Top	4	2	2	2	1	1
		Bottom	4	2	2	2	1	1
EP4CGX110 EP4CGX150	484-pin FBGA	Right	4	2	2	2	1	1
		Top	4	2	2	2	1	1
		Bottom	4	2	2	2	1	1
	672-pin FBGA	Right	4	2	2	2	1	1
		Top	4	2	2	2	1	1
		Bottom	4	2	2	2	1	1
	896-pin FBGA	Right	6	3	2	2	1	1
		Top	6	3	3	3	1	1
		Bottom	6	3	3	3	1	1

Notes to Table 7–1:

(1) Some of the DQ pins can be used as RUP and RDN pins. You cannot use these groups if you are using these pins as RUP and RDN pins for OCT calibration.

(2) Some of the DQ pins can be used as RUP pins while the DM pins can be used as RDN pins. You cannot use these groups if you are using the RUP and RDN pins for OCT calibration.

(3) Only available for EP4CGX30 device.

Figure 7–3 shows the location and numbering of the DQS, DQ, or CQ# pins in I/O banks of the Cyclone IV GX device in the 324-pin FBGA package only.

Figure 7–3. DQS, CQ, or CQ# Pins for Cyclone IV GX Devices in the 324-Pin FBGA Package

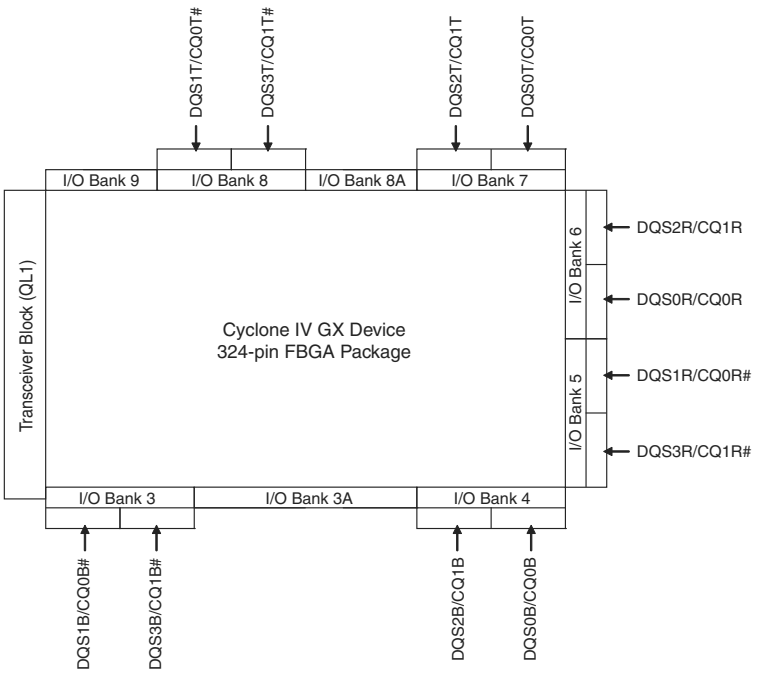
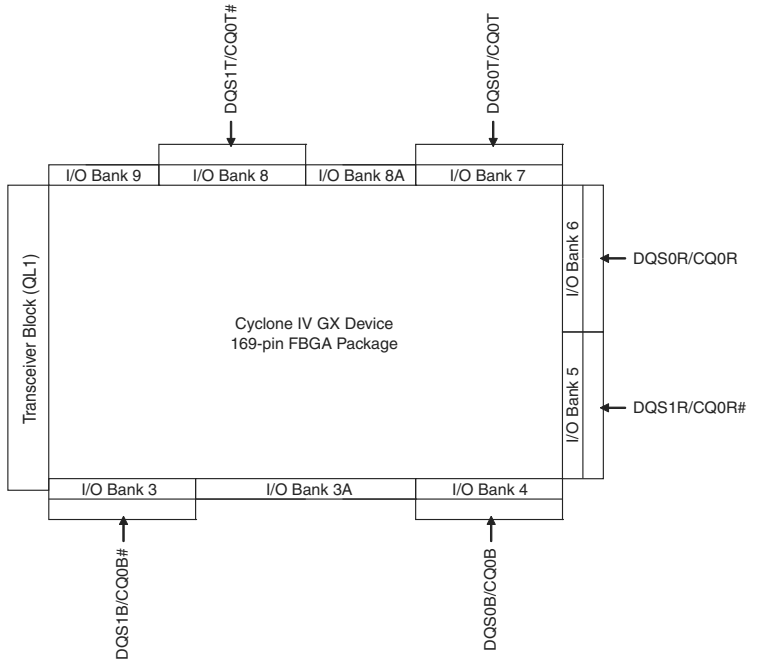


Figure 7–4 shows the location and numbering of the DQS, DQ, or CQ# pins in I/O banks of the Cyclone IV GX device in the 169-pin FBGA package.

Figure 7–4. DQS, CQ, or CQ# Pins for Cyclone IV GX Devices in the 169-Pin FBGA Package



Altera recommends putting a buffer before the DATA and DCLK output from the master device to avoid signal strength and signal integrity issues. The buffer must not significantly change the DATA-to-DCLK relationships or delay them with respect to other AS signals (ASDI and nCS). Also, the buffer must only drive the slave devices to ensure that the timing between the master device and the serial configuration device is unaffected.

This configuration method supports both compressed and uncompressed **.sof**. Therefore, if the configuration bitstream size exceeds the capacity of a serial configuration device, you can enable the compression feature in the **.sof** or you can select a larger serial configuration device.

Guidelines for Connecting a Serial Configuration Device to Cyclone IV Devices for an AS Interface

For single- and multi-device AS configurations, the board trace length and loading between the supported serial configuration device and Cyclone IV device must follow the recommendations listed in Table 8–7.

Table 8–7. Maximum Trace Length and Loading for AS Configuration

Cyclone IV Device AS Pins	Maximum Board Trace Length from a Cyclone IV Device to a Serial Configuration Device (Inches)		Maximum Board Load (pF)
	Cyclone IV E	Cyclone IV GX	
DCLK	10	6	15
DATA[0]	10	6	30
nCSO	10	6	30
ASDO	10	6	30

Note to Table 8–7:

(1) For multi-devices AS configuration using Cyclone IV E with 1,0 V core voltage, the maximum board trace-length from the serial configuration device to the junction-split on both DCLK and Data0 line is 3.5 inches.

Estimating AS Configuration Time

AS configuration time is dominated by the time it takes to transfer data from the serial configuration device to the Cyclone IV device. This serial interface is clocked by the Cyclone IV device DCLK output (generated from a 40-MHz internal oscillator for Cyclone IV E devices, a 20- or 40-MHz internal oscillator, or an external CLKUSR of up to 40 MHz for Cyclone IV GX devices).

Equation 8–2 and Equation 8–3 show the configuration time calculations.

Equation 8–2.

$$\text{Size} \times \left(\frac{\text{maximum DCLK period}}{\text{1 bit}}\right) = \text{estimated maximum configuration ti}$$

Equation 8–3.

$$9{,}600{,}000 \text{ bits} \times \left(\frac{50 \text{ ns}}{\text{1 bit}}\right) = 480 \text{ ms}$$

Table 8–8 provides the configuration time for AS configuration.

Table 8–8. AS Configuration Time for Cyclone IV Devices (1)

Symbol	Parameter	Cyclone IV E	Cyclone IV GX	Unit
t_{SU}	Setup time	10	8	ns
t_H	Hold time	0	0	ns
t_{CO}	Clock-to-output time	4	4	ns

Note to Table 8–8:

(1) For the AS configuration timing diagram, refer to the *Serial Configuration (EPCS) Devices Datasheet*.

Enabling compression reduces the amount of configuration data that is sent to the Cyclone IV device, which also reduces configuration time. On average, compression reduces configuration time by 50%.

Programming Serial Configuration Devices

Serial configuration devices are non-volatile, flash memory-based devices. You can program these devices in-system with the USB-Blaster™ or ByteBlaster™ II download cables. Alternatively, you can program them with the Altera Programming Unit (APU), supported third-party programmers, or a microprocessor with the SRunner software driver.

You can perform in-system programming of serial configuration devices through the AS programming interface. During in-system programming, the download cable disables device access to the AS interface by driving the nCE pin high. Cyclone IV devices are also held in reset by a low level on nCONFIG. After programming is complete, the download cable releases nCE and nCONFIG, allowing the pull-down and pull-up resistors to drive V_{CC} and GND, respectively.

To perform in-system programming of a serial configuration device through the AS programming interface, you must place the diodes and capacitors as close as possible to the Cyclone IV device. You must ensure that the diodes and capacitors maintain a maximum AC voltage of 4.1 V (Figure 8–6).

If you want to use the setup shown in Figure 8–6 to perform in-system programming of a serial configuration device and single- or multi-device AS configuration, you do not require a series resistor on the DATA line at the near end of the serial configuration device. The existing diodes and capacitors are sufficient.

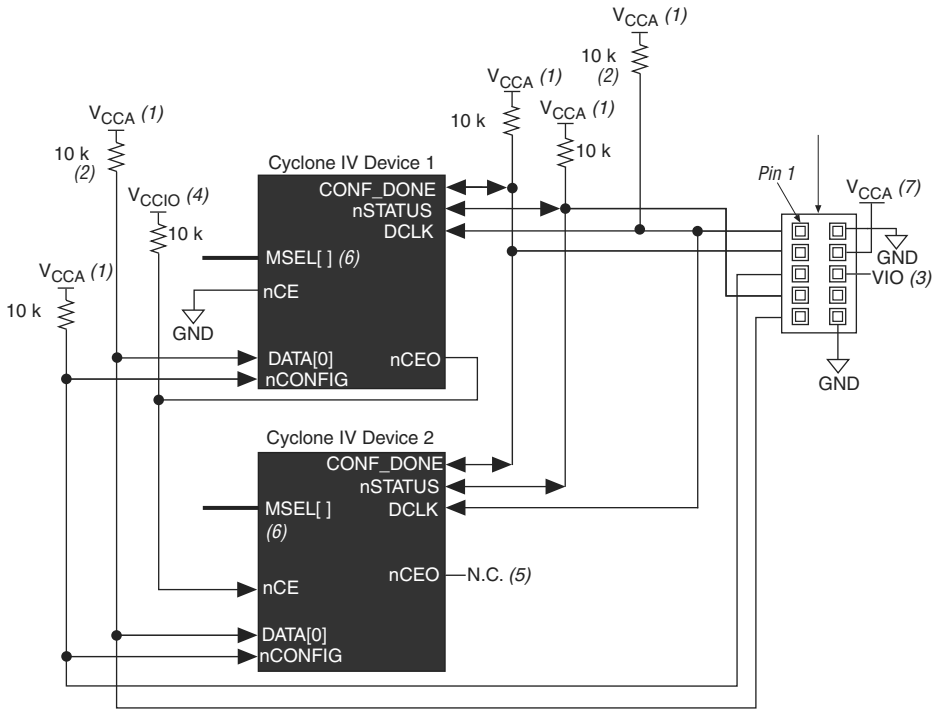
Altera has developed the Serial FlashLoader (SFL), a JTAG-based in-system programming solution for Altera serial configuration devices. The SFL is a bridge design for the Cyclone IV device that uses its JTAG interface to access the EPCS JIC (JTAG Indirect Configuration Device Programming) file and then uses the AS interface to program the EPCS device. Both the JTAG interface and AS interface are bridged together inside the SFL design.

For more information about implementing the SFL with Cyclone IV devices, refer to *AN 370: Using the Serial FlashLoader with the Quartus II Software*.

You can use a download cable to configure multiple Cyclone IV device configuration pins. nCONFIG, nSTATUS, DCLK, DATA[0], and CONF_DONE are connected to every device in the chain. All devices in the chain utilize and enter user mode at the same time because all CONF_DONE pins are tied together.

In addition, the entire chain halts configuration if any device detects an error because the nSTATUS pins are tied together. Figure 8–18 shows the PS configuration for multiple Cyclone IV devices using a MasterBlaster, USB-Blaster, ByteBlaster II, or ByteBlasterMV cable.

Figure 8–18. Multi-Device PS Configuration Using a Download Cable



Notes to Figure 8–18:

(1) You must connect the pull-up resistor to the same supply voltage as the V_{CCA} supply.

(2) The pull-up resistors on DATA[0] and DCLK are only required if the download cable is the only configuration scheme used on your board. This ensures that DATA[0] and DCLK are not left floating after configuration. For example, if you also use a configuration device, the pull-up resistors on DATA[0] and DCLK are not required.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the ByteBlasterMV download cable, this pin is a no connect. When using USB-Blaster, ByteBlaster II, and EthernetBlaster cables, this pin is connected to nCE when it is used for AS programming. Otherwise, it is a no connect.

(4) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the nCE pin resides.

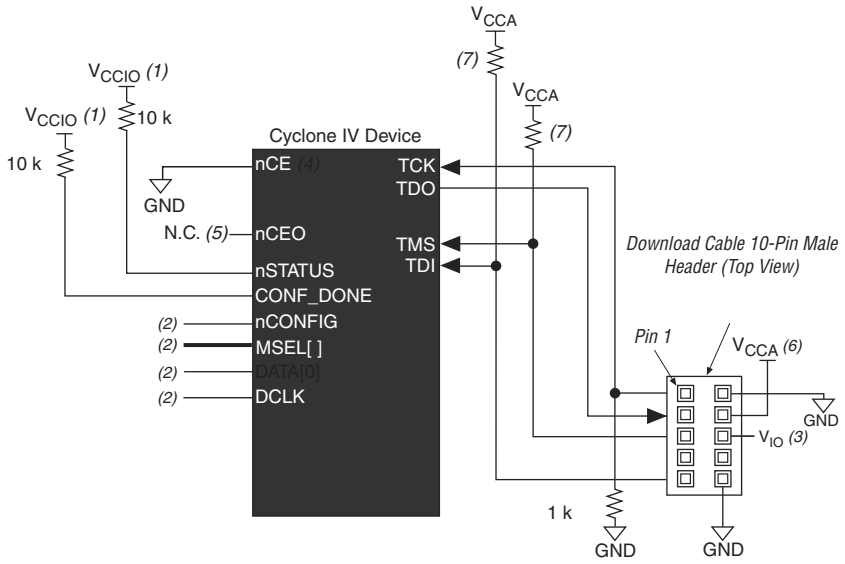
(5) The nCEO pin of the last device in the chain is left unconnected or used as a user I/O pin.

(6) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect MSEL for PS configuration schemes, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(7) Power up the V_{CC} of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5 V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

For device using V_{CCIO} of 2.5, 3.0, and 3.3 V, refer to Figure 8–23. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using V_{CCIO} of 2.5, 3.0, and 3.3 V. You must power up the V_{CC} of the download cable with a 2.5-V supply from V_{CCA}. For device using V_{CCIO} of 1.2, 1.5, and 1.8 V, refer to Figure 8–24. You can power up the V_{CC} of the download cable with the supply from V_{CCIO}.

Figure 8–23. JTAG Configuration of a Single Device Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–23:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the `nCONFIG` and `MSEL` pins to support a non-JTAG configuration scheme. If you only use JTAG configuration, connect the `nCONFIG` pin to logic-high and the `MSEL` pins to GND. In addition, pull `DCLK` and `DATA[0]` to either high or low, whichever is convenient on your board.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the device's V_{CCA}. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the USB-Blaster, ByteBlaster II, ByteBlasterMV, and EthernetBlaster cables, this pin is a no connect.

(4) The `nCE` pin must be connected to GND or driven low for successful JTAG configuration.

(5) The `nCEO` pin is left unconnected or used as a user I/O pin when it does not feed the `nCE` pin of another device.

(6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(7) Resistor value can vary from 1 kΩ to 10 kΩ..

9. SEU Mitigation in Cyclone IV Devices

CYIV-51009-1.3

This chapter describes the cyclical redundancy check (CRC) error detection feature in user mode and how to recover from soft errors.

☞ Configuration error detection is supported in all Cyclone® IV devices including Cyclone IV GX devices, Cyclone IV E devices with 1.0-V core voltage, and Cyclone IV E devices with 1.2-V core voltage. However, user mode error detection is only supported in Cyclone IV GX devices and Cyclone IV E devices with 1.2-V core voltage.

Dedicated circuitry built into Cyclone IV devices consists of a CRC error detection feature that can optionally check for a single-event upset (SEU) continuously and automatically.

In critical applications used in the fields of avionics, telecommunications, system control, medical, and military applications, it is important to be able to:

- Confirm the accuracy of the configuration data stored in an FPGA device
- Alert the system to an occurrence of a configuration error

Using the CRC error detection feature for Cyclone IV devices does not impact fitting or performance.

This chapter contains the following sections:

- "Configuration Error Detection" on page 9–1
- "User Mode Error Detection" on page 9–2
- "Automated SEU Detection" on page 9–3
- "CRC_ERROR Pin" on page 9–3
- "Error Detection Block" on page 9–4
- "Error Detection Timing" on page 9–5
- "Software Support" on page 9–6
- "Recovering from CRC Errors" on page 9–9

Configuration Error Detection

☞ Configuration error detection is available in all Cyclone IV devices including Cyclone IV GX devices, Cyclone IV E devices with 1.0-V core voltage, and Cyclone IV E devices with 1.2-V core voltage.

This chapter provides additional information about the document and Altera.

About this Handbook

This handbook provides comprehensive information about the Altera® Cyclone® IV family of devices.

How to Contact Altera

To locate the most up-to-date information about Altera products, refer to the following table.

Contact (1)	Contact Method	Address
Technical support	Website	www.altera.com/support
Technical training	Website	www.altera.com/training
	Email	custrain@altera.com
Product literature	Website	www.altera.com/literature
Nontechnical support (general)	Email	nacomp@altera.com
(software licensing)	Email	authorization@altera.com

Note to Table:

(1) You can also contact your local Altera sales office or sales representative.

Typographic Conventions

The following table shows the typographic conventions this document uses.

Visual Cue	Meaning
Bold Type with Initial Capital Letters	Indicate command names, dialog box titles, dialog box options, and other GUI labels. For example, **Save As** dialog box. For GUI elements, capitalization matches the GUI.
bold type	Indicates directory names, project names, disk drive names, file names, file name extensions, software utility names, and GUI labels. For example, **\qdesigns** directory, **D:** drive, and **chiptrip.gdf** file.
Italic Type with Initial Capital Letters	Indicate document titles. For example, *Stratix IV Design Guidelines*.
italic type	Indicates variables. For example, *n* + 1. Variable names are enclosed in angle brackets (< >). For example, *<file name>* and *<project name>***.pof** file.
Initial Capital Letters	Indicate keyboard keys and menu names. For example, the Delete key and the Options menu.
"Subheading Title"	Quotation marks indicate references to sections in a document and titles of Quartus II Help topics. For example, "Typographic Conventions."

Table 1–4 lists the synchronization state machine parameters for the word aligner in this mode.

Table 1–4. Synchronization State Machine Parameters

Parameter	Allowed Values
Number of erroneous code groups received to lose synchronization	1–64
Number of continuous good code groups received to reduce the error count by one	1–256

After deassertion of the rx_digitalreset signal in automatic synchronization state machine mode, the word aligner starts looking for the synchronization code groups, word alignment pattern or its complement in the received data stream. When the programmed number of valid synchronization code groups or ordered sets are received, the rx_syncstatus signal is driven high to indicate that synchronization is acquired. The rx_syncstatus signal is constantly driven high until the programmed number of erroneous code groups are received without receiving intermediate good groups; after which the rx_syncstatus signal is driven low. The word aligner indicates loss of synchronization (rx_syncstatus signal remains low) until the programmed number of valid synchronization code groups are received again.

In addition to restoring word boundaries, the word aligner supports the following features:

- Programmable run length violation detection—detects consecutive 1s or 0s in the data stream, and asserts run length violation signal (rx_rlv) when a preset run length threshold (maximum number of consecutive 1s or 0s) is detected. The rx_rlv signal in each channel is clocked by its parallel recovered clock and is asserted for a minimum of two recovered clock cycles to ensure that the FPGA fabric clock can latch the rx_rlv signal reliably because the FPGA fabric clock might have phase differences, ppm differences (in asynchronous systems), or both, with the recovered clock. Table 1–5 lists the run length violation circuit detection capabilities.

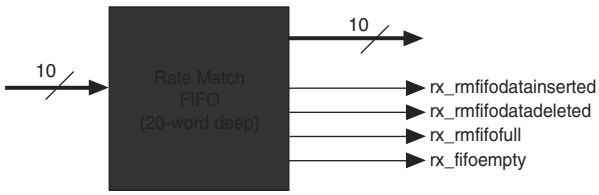
Table 1–5. Run Length Violation Circuit Detection Capabilities

Supported Data Width	Detector Range		Increment Step Settings
	Minimum	Maximum	
8-bit	4	128	4
10-bit	5	160	5

Rate Match FIFO

In asynchronous systems, the upstream transmitter and local receiver can be clocked with independent reference clocks. Frequency differences in the order of a few hundred ppm can corrupt the data when latching from the recovered clock domain (the same clock domain as the upstream transmitter reference clock) to the local receiver reference clock domain. Figure 1–21 shows the rate match FIFO block diagram.

Figure 1–21. Rate Match FIFO Block Diagram



The rate match FIFO compensates for small clock frequency differences of up to ±300 ppm (600 ppm total) between the upstream transmitter and the local receiver clocks by performing the following functions:

- Insert skip symbols when the local receiver reference clock frequency is greater than the upstream transmitter reference clock frequency
- Delete skip symbols when the local receiver reference clock frequency is less than the upstream transmitter reference clock frequency

The 20-word deep rate match FIFO and logics control insertion and deletion of skip symbols, depending on the ppm difference. The operation begins after the word aligner synchronization status (`rx_syncstatus`) is asserted.

Rate match FIFO is only supported with 8B/10B encoded data and the word aligner in automatic synchronization state machine mode.

8B/10B Decoder

The 8B/10B decoder receives 10-bit data and decodes it into an 8-bit data and a 1-bit control identifier. The decoder is compliant with Clause 36 of the IEEE 802.3 specification.

Figure 1–22 shows the 8B/10B decoder block diagram.

Figure 1–22. 8B/10B Decoder Block Diagram

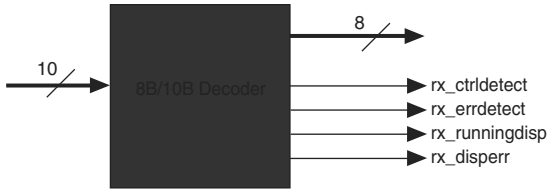
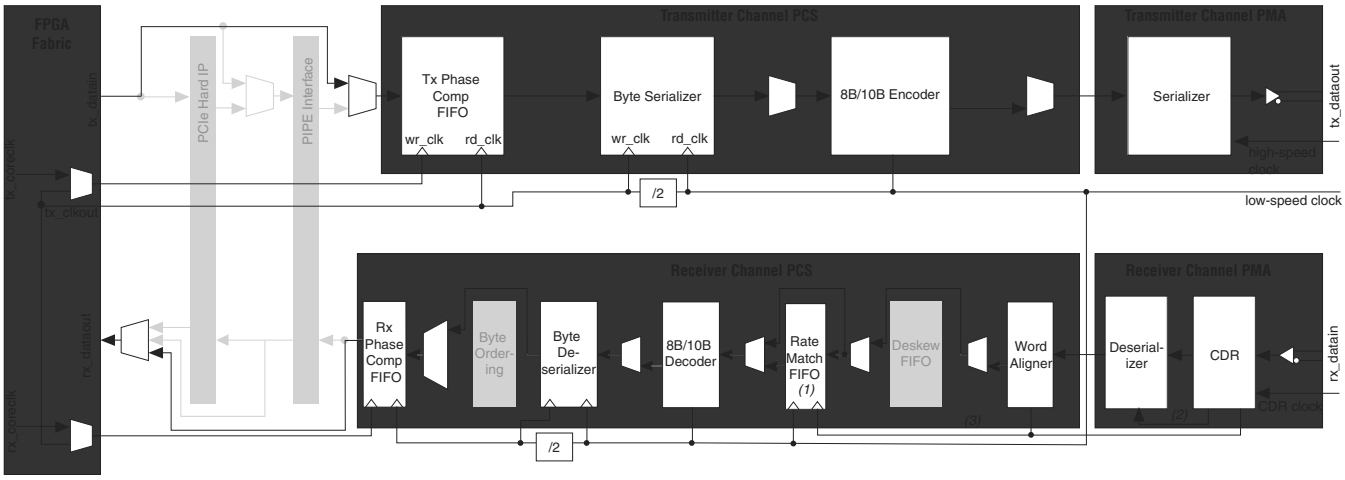


Figure 1–60 shows the transceiver channel datapath and clocking when configured in Serial RapidIO mode.

Figure 1–60. Transceiver Channel Datapath and Clocking when Configured in Serial RapidIO Mode



Notes to Figure 1–60:

(1) Optional rate match FIFO.

(2) High-speed recovered clock.

(3) Low-speed recovered clock.

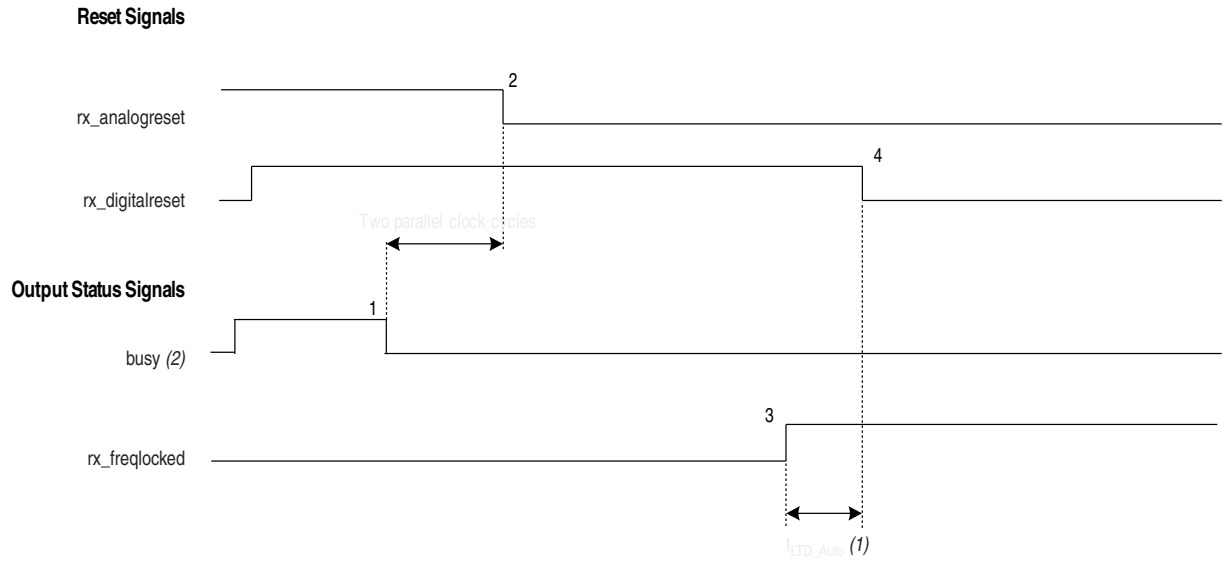
Transmitter Only Channel

This configuration contains only a transmitter channel. If you create a **Transmitter Only** instance in the ALTGX MegaWizard Plug-In Manager, use the same reset sequence shown in Figure 2–3 on page 2–7.

Receiver Only Channel—Receiver CDR in Automatic Lock Mode

This configuration contains only a receiver channel. If you create a **Receiver Only** instance in the ALTGX MegaWizard Plug-In Manager with the receiver CDR in automatic lock mode, use the reset sequence shown in Figure 2–6.

Figure 2–6. Sample Reset Sequence of Receiver Only Channel—Receiver CDR in Automatic Lock Mode



Notes to Figure 2–6:

(1) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(2) The `busy` signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the `busy` signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

As shown in Figure 2–6, perform the following reset procedure for the receiver in CDR automatic lock mode:

1. After power up, wait for the `busy` signal to be deasserted.
2. Keep the `rx_digitalreset` and `rx_analogreset` signals asserted during this time period.
3. After the busy signal is deasserted, wait for another two parallel clock cycles, then deassert the `rx_analogreset` signal.
4. Wait for the `rx_freqlocked` signal to go high.
5. When `rx_freqlocked` goes high (marker 3), from that point onwards, wait for at least t_{LTD_Auto}, then de-assert the `rx_digitalreset` signal (marker 4). At this point, the receiver is ready to receive data.

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 6 of 7)

Port Name	Input/ Output	Description
rx_eqdcgain [1..0] (1)	Input	This is an optional equalizer DC gain write control. The width of this signal is fixed to 2 bits if you enable either the **Use 'logical_channel_address' port for Analog controls reconfiguration** option or the **Use same control signal for all the channels** option in the **Analog controls** screen. Otherwise, the width of this signal is 2 bits per channel. The following values are the legal settings allowed for this signal: rx_eqdcgain[1..0] — Corresponding ALTGX settings — Corresponding DC Gain value (dB) 2'b00 — 0 — 0 2'b01 — 1 — 3 (2) 2'b10 — 2 — 6 All other values => N/A For more information, refer to the "Programmable Equalization and DC Gain" section of the *Cyclone IV GX Device Datasheet* chapter.
tx_vodctrl_out [2..0]	Output	This is an optional transmit V_{OD} read control signal. This signal reads out the value written into the V_{OD} control register. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the **Use 'logical_channel_address' port for Analog controls reconfiguration** option and the **Use same control signal for all the channels** option.
tx_preemp_out [4..0]	Output	This is an optional pre-emphasis read control signal. This signal reads out the value written by its input control signal. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the **Use 'logical_channel_address' port for Analog controls reconfiguration** option and the **Use same control signal for all the channels** option.
rx_eqctrl_out [3..0]	Output	This is an optional read control signal to read the setting of equalization setting of the ALTGX instance. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the **Use 'logical_channel_address' port for Analog controls reconfiguration** option and the **Use same control signal for all the channels** option.
rx_eqdcgain_out [1..0]	Output	This is an optional equalizer DC gain read control signal. This signal reads out the settings of the ALTGX instance DC gain. The width of this output signal depends on the number of channels controlled by the dynamic reconfiguration controller and also the configuration of the **Use 'logical_channel_address' port for Analog controls reconfiguration** option and the **Use same control signal for all the channels** option.
Transceiver Channel Reconfiguration Control/Status Signals		
reconfig_mode_ sel[2..0] (3)	Input	Set the following values at this signal to activate the appropriate dynamic reconfiguration mode: 3'b000 = PMA controls reconfiguration mode. This is the default value. 3'b001 = Channel reconfiguration mode All other values => N/A reconfig_mode_sel[] is available as an input only when you enable more than one dynamic reconfiguration mode.

Table 3–5. rx_dataoutfull[31..0] FPGA Fabric-Transceiver Channel Interface Signal Descriptions (Part 2 of 3)

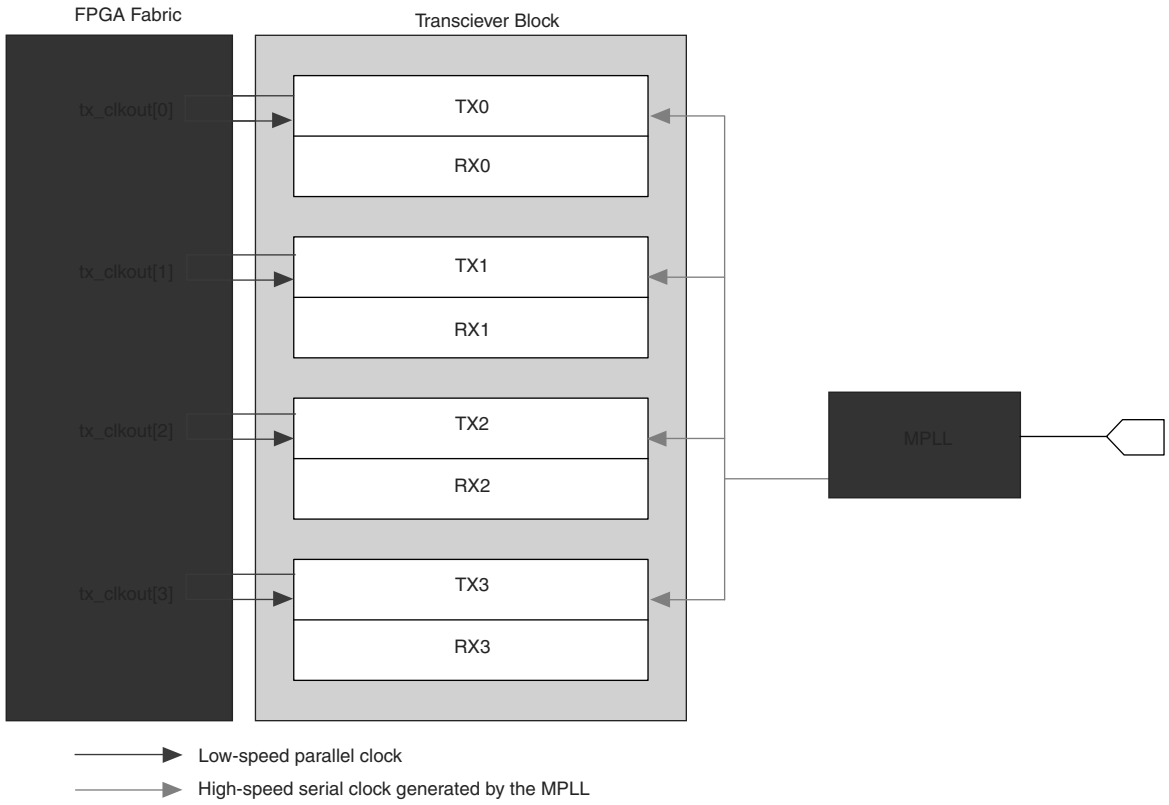
FPGA Fabric-Transceiver Channel Interface Description	Receive Signal Description (Based on Cyclone IV GX Supported FPGA Fabric-Transceiver Channel Interface Widths)
16-bit FPGA fabric-Transceiver Channel Interface with PCS-PMA set to 8/10 bits	Two 8-bit unencoded Data (rx_dataout) rx_dataoutfull[7:0] - rx_dataout (LSByte) and rx_dataoutfull[23:16]- rx_dataout (MSByte)
	The following signals are used in 16-bit 8B/10B modes:
	Two Control Bits rx_dataoutfull[8] - rx_ctrldetect (LSB) and rx_dataoutfull[24]- rx_ctrldetect (MSB)
	Two Receiver Error Detect Bits rx_dataoutfull[9] - rx_errdetect (LSB) and rx_dataoutfull[25]- rx_errdetect (MSB)
	Two Receiver Sync Status Bits rx_dataoutfull [10] - rx_syncstatus (LSB) and rx_dataoutfull[26] - rx_syncstatus (MSB)
	Two Receiver Disparity Error Bits rx_dataoutfull [11] - rx_disperr (LSB) and rx_dataoutfull[27] - rx_disperr (MSB)
	Two Receiver Pattern Detect Bits rx_dataoutfull[12] - rx_patterndetect (LSB) and rx_dataoutfull[28]- rx_patterndetect (MSB)
	rx_dataoutfull[13] and rx_dataoutfull[29]: Rate Match FIFO deletion status indicator (rx_rmfifodatadeleted) in non-PCI Express (PIPE) functional modes
	rx_dataoutfull[14] and rx_dataoutfull[30]: Rate Match FIFO insertion status indicator (rx_rmfifodatainserted) in non-PCI Express (PIPE) functional modes
	Two 2-bit PCI Express (PIPE) Functional Mode Status Bits rx_dataoutfull[14:13] - rx_pipestatus (LSB) and rx_dataoutfull[30:29] - rx_pipestatus (MSB)
	rx_dataoutfull[15] and rx_dataoutfull[31]: 8B/10B running disparity indicator (rx_runningdisp)

Option 2: Use the Respective Channel Transmitter Core Clocks

- Enable this option if you want the individual transmitter channel `tx_clkout` signals to provide the write clock to their respective Transmit Phase Compensation FIFOs.
- This option is typically enabled when each transceiver channel is reconfigured to a different functional mode using channel reconfiguration.

Figure 3–12 shows how each transmitter channel's `tx_clkout` signal provides a clock to the Transmit Phase Compensation FIFOs of the respective transceiver channels.

Figure 3–12. Option 2 for Transmitter Core Clocking (Channel Reconfiguration Mode)



Receiver core clocking refers to the clock that is used to read the parallel data from the Receiver Phase Compensation FIFO into the FPGA fabric. You can use one of the following clocks to read from the Receive Phase Compensation FIFO:

- `rx_coreclk`—you can use a clock of the same frequency as `rx_clkout` from the FPGA fabric to provide the read clock to the Receive Phase Compensation FIFO. If you use `rx_coreclk`, it overrides the `rx_clkout` options in the ALTGX MegaWizard Plug-In Manager.
- `rx_clkout`—the Quartus II software automatically routes `rx_clkout` to the FPGA fabric and back into the Receive Phase Compensation FIFO.

Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1–12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

Table 1–12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices *(1)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\_PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	V_{CCIO} = 3.3 V ± 5% *(2), (3)*	7	25	41	kΩ
		V_{CCIO} = 3.0 V ± 5% *(2), (3)*	7	28	47	kΩ
		V_{CCIO} = 2.5 V ± 5% *(2), (3)*	8	35	61	kΩ
		V_{CCIO} = 1.8 V ± 5% *(2), (3)*	10	57	108	kΩ
		V_{CCIO} = 1.5 V ± 5% *(2), (3)*	13	82	163	kΩ
		V_{CCIO} = 1.2 V ± 5% *(2), (3)*	19	143	351	kΩ
$R_{\_PD}$	Value of the I/O pin pull-down resistor before and during configuration	V_{CCIO} = 3.3 V ± 5% *(4)*	6	19	30	kΩ
		V_{CCIO} = 3.0 V ± 5% *(4)*	6	22	36	kΩ
		V_{CCIO} = 2.5 V ± 5% *(4)*	6	25	43	kΩ
		V_{CCIO} = 1.8 V ± 5% *(4)*	7	35	71	kΩ
		V_{CCIO} = 1.5 V ± 5% *(4)*	8	50	112	kΩ

Notes to Table 1–12:

(1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.

(2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(3) $R_{\_PU} = (V_{CCIO} – V_I)/I_{R\_PU}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, $V_I = V_{CC}$ + 5% – 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, V_I = 0 V;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, V_I = 0 V; in which V_I refers to the input voltage at the I/O pin.

(4) $R_{\_PD} = V_I/I_{R\_PD}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, V_I = 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, $V_I = V_{CC}$ – 5%;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, $V_I = V_{CC}$ – 5%; in which V_I refers to the input voltage at the I/O pin.

Hot-Socketing

Table 1–13 lists the hot-socketing specifications for Cyclone IV devices.

Table 1–13. Hot-Socketing Specifications for Cyclone IV Devices

Symbol	Parameter	Maximum
$I_{IOPIN(DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN(AC)}$	AC current per I/O pin	8 mA *(1)*
$I_{XCVRTX(DC)}$	DC current per transceiver TX pin	100 mA
$I_{XCVRRX(DC)}$	DC current per transceiver RX pin	50 mA

Note to Table 1–13:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |IIOPIN| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

☞ During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.